

.D.

Shanghai International College of  
Electronics Technology University  
Technology Electronics Laboratory  
IP Development & Research Center, School of Electronics  
Packaging Office (Assembly)  
China Science and Technology Packaging Research  
Center, Technology University (Assembly)  
Innovation & Packaging Center; Electronics Packaging  
Technology; Packaging Center; Packaging and Packaging Technology

E-mail: [\\_\\_\\_\\_\\_@\\_\\_\\_\\_\\_](mailto:_____@_____)

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